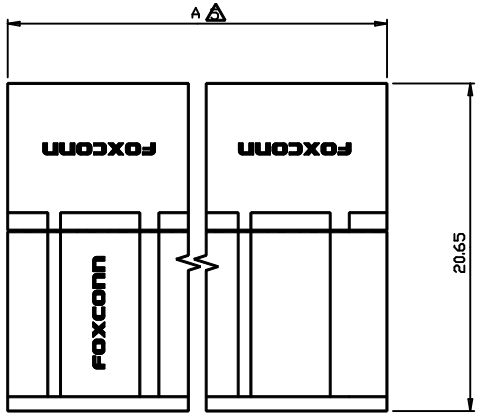
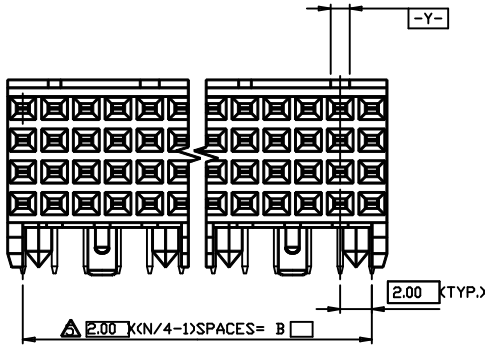
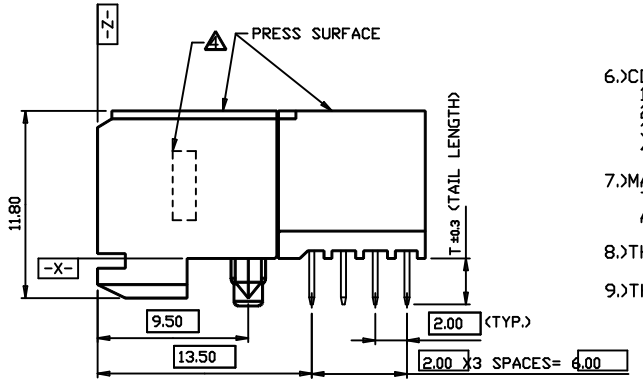
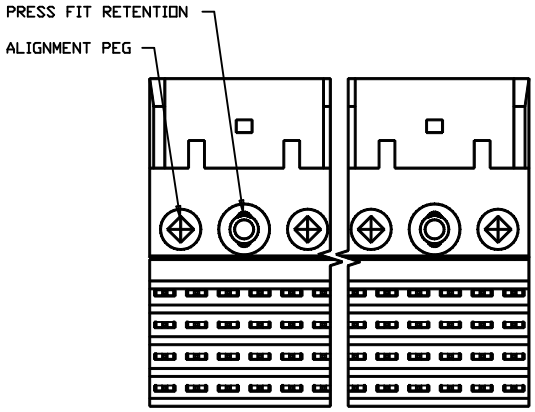
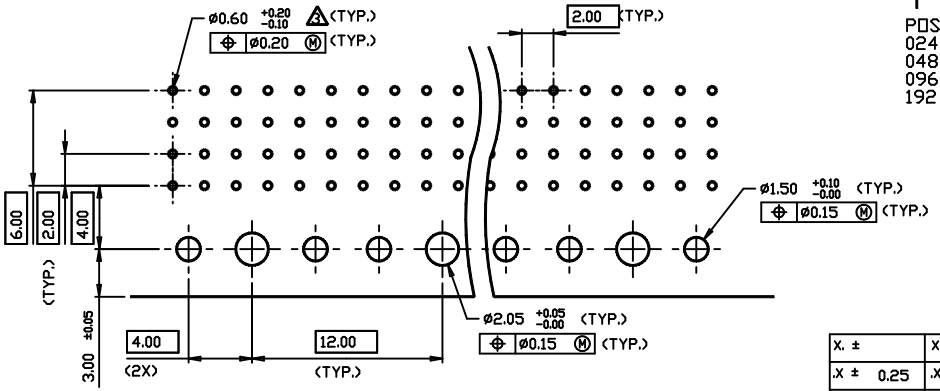
REV.	ECN. NO.	APPD.
A	HC001692	











RECOMMENDED PCB LAYOUT
(COMPONENT SIDE)

NOTES:

1.)HOUSING MATERIAL:THERMALPLASTIC, WHITE,UL 94V-0

2.)CONTACT MATERIAL:PHOSPHOR BRONZE.
- 1.50u" MIN. NICKEL UNDER PLATING OVER ALL.
- 2.150u" MIN. Sn/Pb PLATING ON SOLDER AREA.
- 3.30u" Min.Au OVER 10u" Min.Pd/Ni PLATING ON MATING AREA.

3.)SOLDER HOLES:
- 1.HOLE DIAMETER AFTER PLATING 0.50-0.80mm.
- 2.DRILLED HOLE:0.66-0.86mm.
- 3.COPPER PLATING:0.025mm MIN.
- 4.TIN/LEAD PLATING:0.005-0.015mm.

4.)PART MARKING,FOXCONN DATE CODE.

5.)THE DIMENSION LIST OF PARAMETERS A & B:

NO. OF POS.	DIM A	DIM B
24	11.90	10.00
48	23.90	22.00
96	47.90	46.00
192	95.90	94.00

6.)CONNECTOR RATING(WHEN MATING):
- 1.CURRENT RATING:1 A MAX. PER CONTACT WITH ALL CONTACTS ENERGIZED.
- 2.RATED VOLTAGE:750 V A.C.
- 3.OPERATING TEMPERATURE:-55°C TO 125°C.
- 4.DIELECTRIC WITHSTANDING VOLTAGE:1000 V A.C.

7.)MATING CONDITION:
THE MATING FORCE OF HEADER & REC.IS 0.45 N MAX. PER PIN AND THE UNMATING FORCE IS 0.15 N MIN. PER PIN.

8.)THE MIN. CONTACT HERTZ STRESS REQUIREMENT IS 150 KPSI.

9.)THE OTHER MONOBLOCK SIZES ARE AVAILABLE UPON REQUEST.

PART LIST

1 F 1 2 * * * K - S * 0 1

POS. NO.
024 : 24 POS.
048 : 48 POS.
096 : 96 POS.
192 :192 POS.

TAIL LENGTH (T)
2: 2.73mm
3: 3.53mm

X. ±	X.° ±	UNITS mm	NAME(INTENDED USE) FUTURE BUS RECEPTACLE	FOXCONN HON HAI PRECISION IND. CO.,LTD. TAIPEI, TAIWAN, R.O.C.	
.X ± 0.25	.X ° ±	MAT'L			
.XX ± 0.15	.XX ° ±		PART NO.(INTENDED USE) 1F12***K-S*01	TITLE: CUSTOMER DRAWING 4 ROWS,SOLDER LEAD	
.XXX ±	.XXX ° ±	FINISH	APPD:	DWG NO. 343-0000-048	
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.		Q'TY	CHKD:	SCALE N/A	SHEET 1/2 REV. A
			DR:		